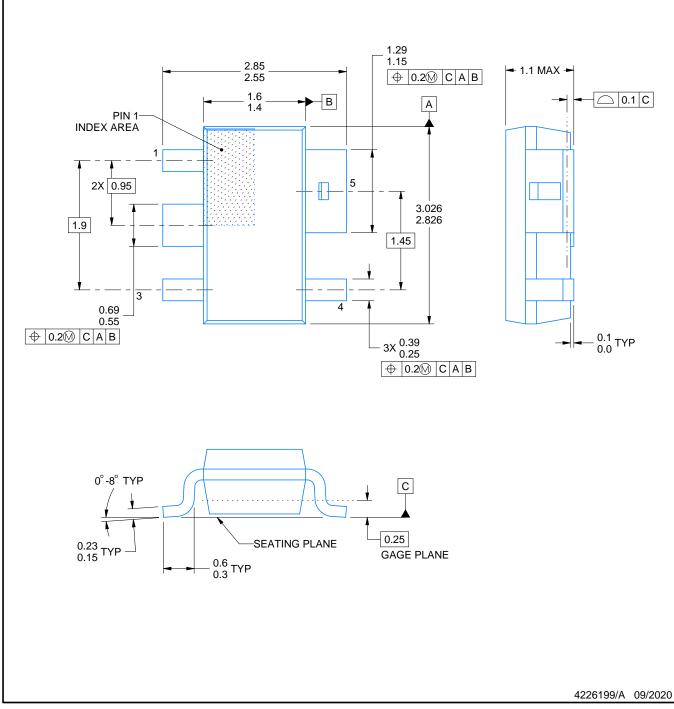
DYB0005A



PACKAGE OUTLINE

SOT - 1.1 max height





NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 This drawing is subject to change without notice.
 No JEDEC reference as of August 2020.

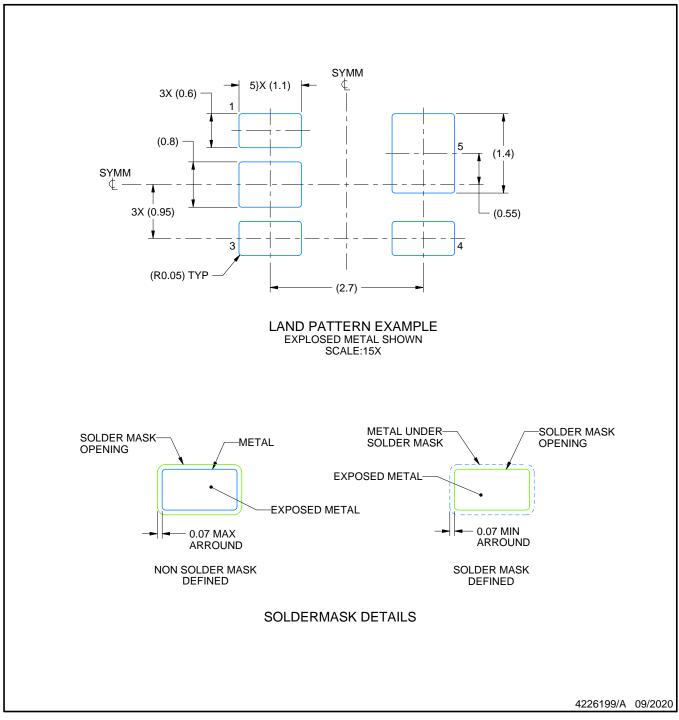


DYB0005A

EXAMPLE BOARD LAYOUT

SOT - 1.1 max height

SOT



NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.

5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

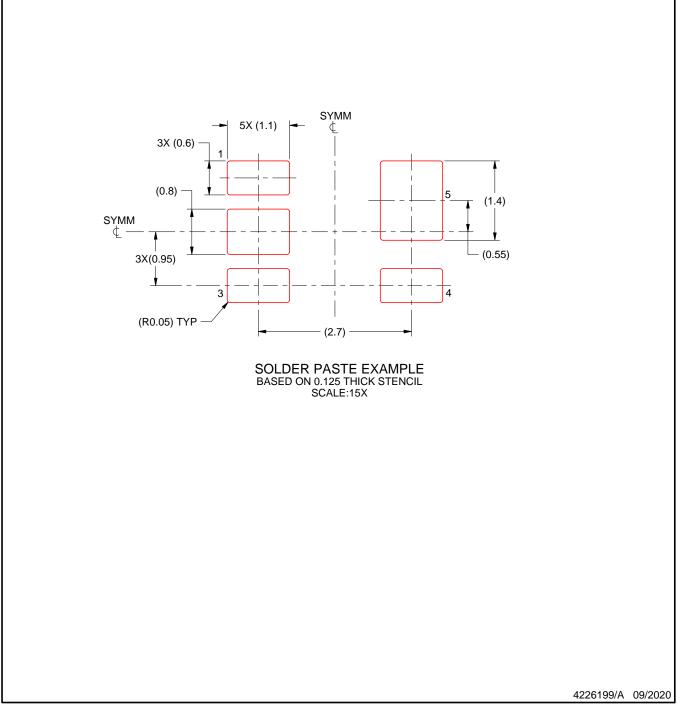


DYB0005A

EXAMPLE STENCIL DESIGN

SOT - 1.1 max height

SOT



NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations. 7. Board assembly site may have different recommendations for stencil design.



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